Qualification Test Report 501-5583 30 Aug'04 Rev.O

1. INTRODUCTION

1.1 Testing was performed on the USB Connector to determine if it meets the requirements of

Product Specification 108-5983 Rev.A.

1.2 Scope

This report covers the electrical, mechanical, and environmental performance of the USB Connector.

The qualification testing was performed between 26-Jul-2004 and 09-Aug-2004.

1.3 Conclusion

USB Connector meets the electrical, mechanical and environmental performance requirements of Product Specification 108-5983 Rev.A.

1.4 Product Description

This product have been designed under "USB" specification.

1.5 Test Samples

Samples were taken randomly from current production ,The following samples were used:

Part Number	Description
1746311-1	USB CONNECTOR
974325-X	Standard Cable Ass'y,USB Plug, 4Pos4Pos.

FIG.1

2. TEST CONTENTS

. TES	CONTENTS							
Para.	Test Items	Requirements	Judgement					
2.1	Examination of Product	Visual Inspection No physical damage	Acceptable					
2.2	Examination of Plating	Meets plating specification of product drawing.	Acceptable					
		Electrical Requirements						
Termination 2.3 Resistance (Low Level) Termination 30 mΩ Max.								
2.4	Dielectric withstanding Voltage	Initial/Final; 750V AC, (50 Hz), 1 minute No abnormality allowed. Current leakage:1 mA Max.	Acceptable					
2.5	Insulation Resistance	Impressed voltage 500 VDC Initial ; $1000M\Omega$ Min. Final ; $1000M\Omega$ Min.						
2.6	Capacitance	Acceptable						
		Mechanical Requirements						
2.7	Vibration (Random)	Vibration Frequency: 50 to 2000 Hz Accelerated Velocity:52.43m/s²(5.35G) Random Vibration X, Y & Z Axes: 15 minute each, 1A applied. No electrical discontinuity greater than 1µ sec. shall occur	Acceptable					
2.8	Physical Shock	No electrical discontinuity greater than 1µ sec. allowed. 294 m/s² (30 G), Sawtooth/Halfsine Wave, 11msec. X,Y,Z ± directions each 3 drops, Total 18 drops	Acceptable					
2.9	Connector Mating Force	Operation Speed: 12.5mm/min. 35N(3.57kgf)Max.	Acceptable.					
2.10	Connector Un-mating Force	Operation Speed: 12.5mm/min. 10N(1kgf)Min.	Acceptable.					
2.11	Contact Retention Force	3N(0.31kgf)Min. Apply an axial pull-off load to contact (at least 5 seconds)	Acceptable					

Fig.2 (to be continued)

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Para.	Test Items	Requirements	Judgement
2.12	Durability (Repeated Mate / Un-mating)	Operation Speed:200 cycles/hr. No. of Cycles: 1500 cycles	Acceptable
2.13	Resistance to Soldering Heat	Test connector on PCB. Flow Soldering Solder Temperature : 260±5°C Immersion Duration in Solder : 10±0.5 seconds Manual Soldering Temperature: 350±10°C for 3(+1/-0) Seconds. No physical damage shall occur.	Acceptable
2.14	Solderability	Solder Temperature : 245±3 °C Immersion Duration in Solder : 3±0.5 seconds Immersion Duration in Flux : 5 ~ 10 seconds Solder Sample : Sn-3Ag-0.5Cu Flux Sample : Tamura Chemical Ind. NA-200 (Suitable) Wet solder coverage: 95% Min.	Acceptable
		Environmental Requirements	
2.15	Thermal Shock	-55°C / 30min., + 85°C / 30min. Making this a cycle, repeat 5 cycles. Insulation resistance 1000MΩ Min.(Final) To meet Dielectric withstanding Voltage.	Acceptable
2.16	Humidity, Steady State	90 ~ 95%R.H. 40°C 96hours Insulation resistance 1000MΩ Min.(Final) To meet Dielectric withstanding Voltage	Acceptable
2.17	Temperature Life (Heat Aging)	85°C, 250hours 30 mΩ Max.	Acceptable
2.18	Examination of Whisker-1 (Thermal Shock)	-35±5°C / 30min., + 125±5°C / 30min. Making this a cycle, repeat 500 cycles. No whisker on surface of contact and shell.	Acceptable
2.19	Examination of Whisker-2 (Humidity, Steady State)	85%R.H. 85°C 500hours No whisker on surface of contact and shell.	Acceptable

Fig.2(End)

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3. PRODUCT QUALIFICATION TEST SEQUENCE

				Te	st Gro	up				
Test Items	1	2	3	4	5	6	7	8	9	
	Test Sequence(a)									
Examination of Product	1,9	1,6	1,9	1,3	1,3	1	1,3	1,3	1,3	
Examination of Plating						2				
Termination Resistance	3,7	2,5								
Dielectric Withstanding Voltage			4,8							
Insulation Resistance			3,7							
Capacitance			2							
Vibration(Random)	5									
Physical Shock	6									
Connector Mating Force	2									
Connector Unmating Force	8									
Contact Retention Force					2					
Durability (Repeated Mate/Unmating)	4	3(b)								
Resistance to Soldering Heat							2			
Solderability				2						
Thermal Shock			5							
Humidity(Steady State)			6							
Temperature Life(Heat Aging)		4								
Examination of Whisker-1 (Thermal Shock)								2		
Examination of Whisker-2 (Humidity,Steady State)									2	

(a) Numbers indicate sequence in which the tests are performed.

(b) Just 10 cycles durability

Fig.3

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4. TEST RESULT

	Test Group 1											
Conditions	Mose	Measure Item		11-4		Res	sults	D	l. dl			
Conditions	IVICAS	ure nem	N	Unit	MAX	MIN	AVE	σ	Requirement	Judgment		
Initial	Termination Resistance		20	mΩ	19.77	15.46	16.94	1.32	30 mΩ Max	Acceptable		
After Physical Shock	Termination Resistance		20	mΩ	20.14	15.49	16.90	1.21	30 mΩ Max	Acceptable		
After Vibration (Random)	Circuit Continuity (During Test)		5	μs		No Disc	ontinuity	1 μ s sec.Max	Acceptable			
After Physical Shock	Con	rcuit itinuity ng Test)	5	μs		No Disc	ontinuity	1 μ s sec.Max	Acceptable			
	Initial	Mating	5	N	14.9	11.6	13.58	1.25	35N Max	Acceptable		
Connector Mating/	iiiiliai	Un- mating	5	N	27.5	22.0	25.58	2.22	10N Min.	Acceptable		
Un-mating Force	Final (1500	Mating	5	N	13.9	9.9	11.90	1.93	35N Max	Acceptable		
	times)	Un- mating	5	N	17.9	12.7	16.00	2.41	10N Min.	Acceptable		

	Test Group 2										
		N	Unit		Res	sults		Requirement			
Conditions	Measure Item			MAX	MIN	AVE	σ		Judgment		
Initial	Termination Resistance	20	mΩ	19.11	14.80	16.53	1.08	30 mΩ Max	Acceptable		
After Temperature life(Heat Aging)	Termination Resistance	20	mΩ	26.09	13.87	21.58	3.23	30 mΩ Max	Acceptable		

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				Test	Group 3	ı				
	Measure				Re	sults				
Conditions	Items	N	Unit	MAX	MIN	AVE	σ	Requirement	Judgment	
	Capacitance	20	pF	0.92	0.80	0.860	0.00725	2pF Max	Acceptable	
Initial	Insulation Resistance (Between	20		Ma conn	ited ector	1x10	^{I3} ΩMin	1000MΩ Min	Associable	
	adjacent circuits)	20	Ω		ated ector	1x10 ¹³ ΩMin		TOUCKIS WIII	Acceptable	
	Dielectric Strength (Between adjacent circuits)		20 -		ted ector	1	No malities	No		
		20			Unmated No connector Abnorma		No.	Abnormalities allowed.	Acceptable	
	Insulation Resistance		e	_		Mated 1x10 ¹³ ΩMin		¹³ ΩMin	4000040 845-	
After Humidity(adjacent circuits)	20	Ω		ated ector	1x10 ¹³ ΩMin		1000MΩ Min	Acceptable	
Steady,State)	Dielectric			Ma	ited	1	No	No		
	Strength (Between adjacent	20	_	conn	connector		malities	Abnormalities	Acceptable	
		20	-	Unmated		No		allowed.	Acceptable	
	circuits)			conn	ector	Abnor	malities			

	Test Group 4										
Conditions	Measure Item	N	Unit	Results	Requirement	Judgment					
Solderability	Appearance	5	-	Wet solder coverage:95% Min.	Wet solder coverage: 95% Min.	Acceptable					

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Test Group 5										
Conditions	Measure Item	N	Unit	Results						
				MAX	MIN	AVE	σ	Requirement	Judgment	
Initial	Contact Retention Force	20	N	16.0	9.3	12.90	3.0	3N Min.	Acceptable	

	Test Group 6										
Conditions	Measure Item	N	Unit	Results	Requirement	Judgment					
Initial	Examination of Plating	5	-	Met plating specification of product drawing.	Meets plating specification of product drawing.	Acceptable					

	Test Group 7											
Conditions	Measure Item	N	Unit	Results	Requirement	Judgment						
Initial		5	-	No physical damage	No physical damage shall occur.							
After Resistance to Soldering Heat	Appearance	5	1	No physical damage		Acceptable						

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	Test Group 8											
Conditions	Measure Item	N	Unit	Results	Requirement	Judgment						
Initial	Evamination	5	-	No Whisker	No Whisker							
After Thermal Shock	Examination of Whisker	5	-	No Whisker	contact and shell	Acceptable						

Test Group 9						
Conditions	Measure Item	N	Unit	Results	Requirement	Judgment
Initial	Examination of Whisker	5	-	No Whisker	No Whisker on surface of contact and shell	Acceptable
After Humidity (Steady,State)		5	-	No Whisker		

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